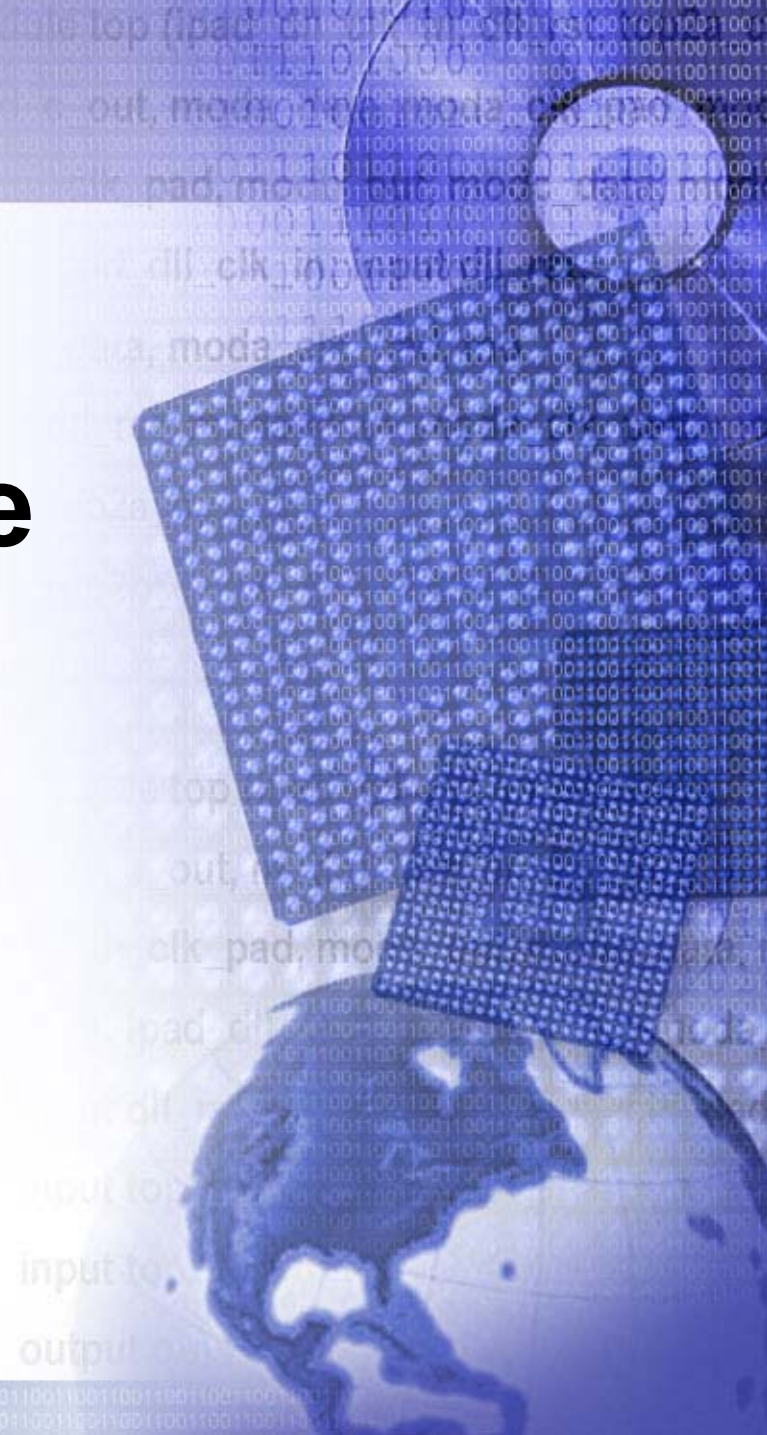


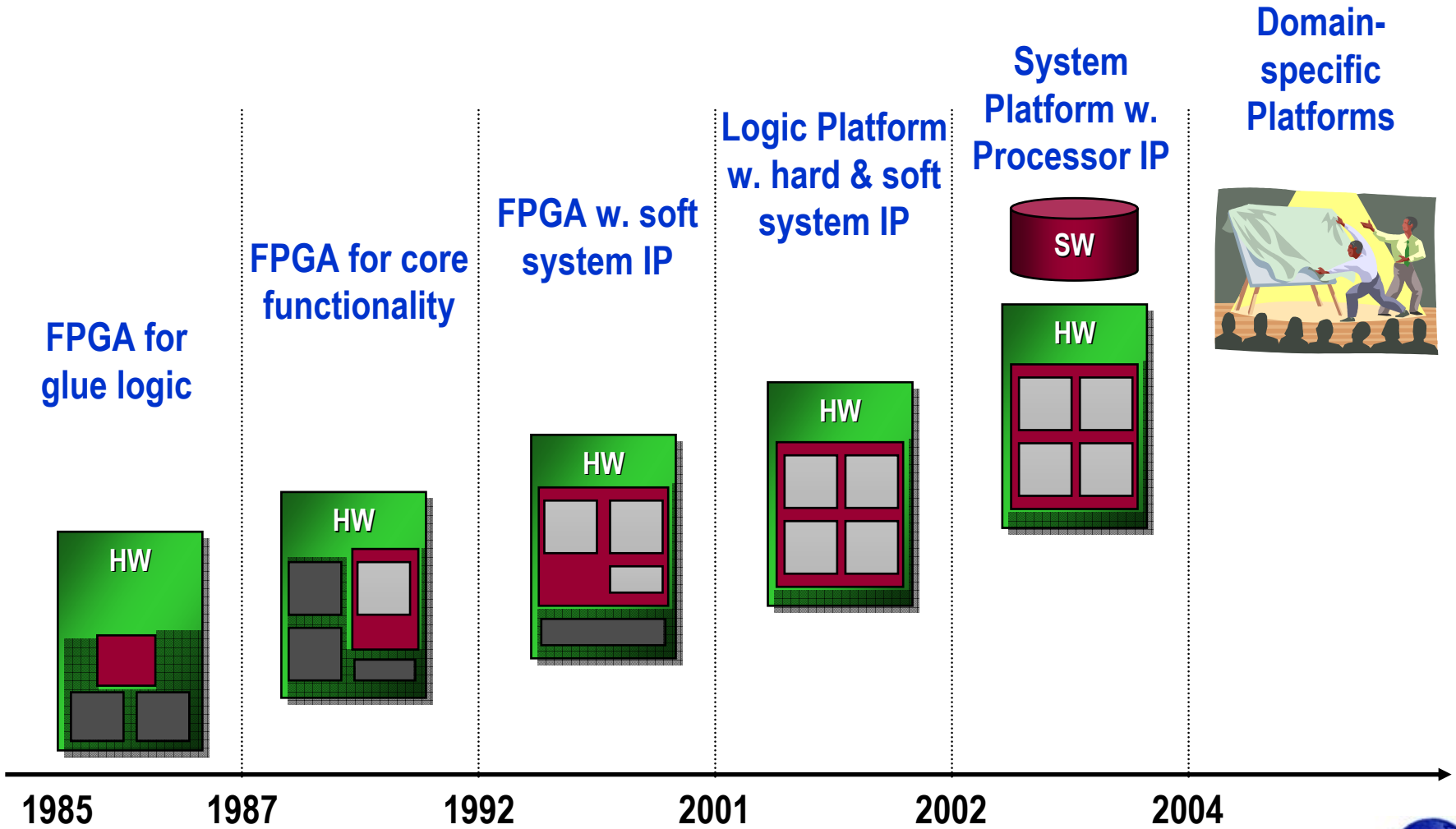


Revolutionary Architecture for the Next Generation Platform FPGAs

*Embargoed News:
December 8, 2003*



The Evolution of FPGA Architectures



■ FPGA Solution

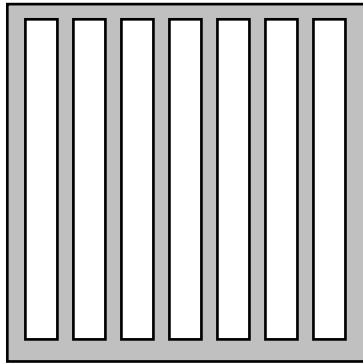
Meta Architecture 2



The ASMBL^(TM) Architecture

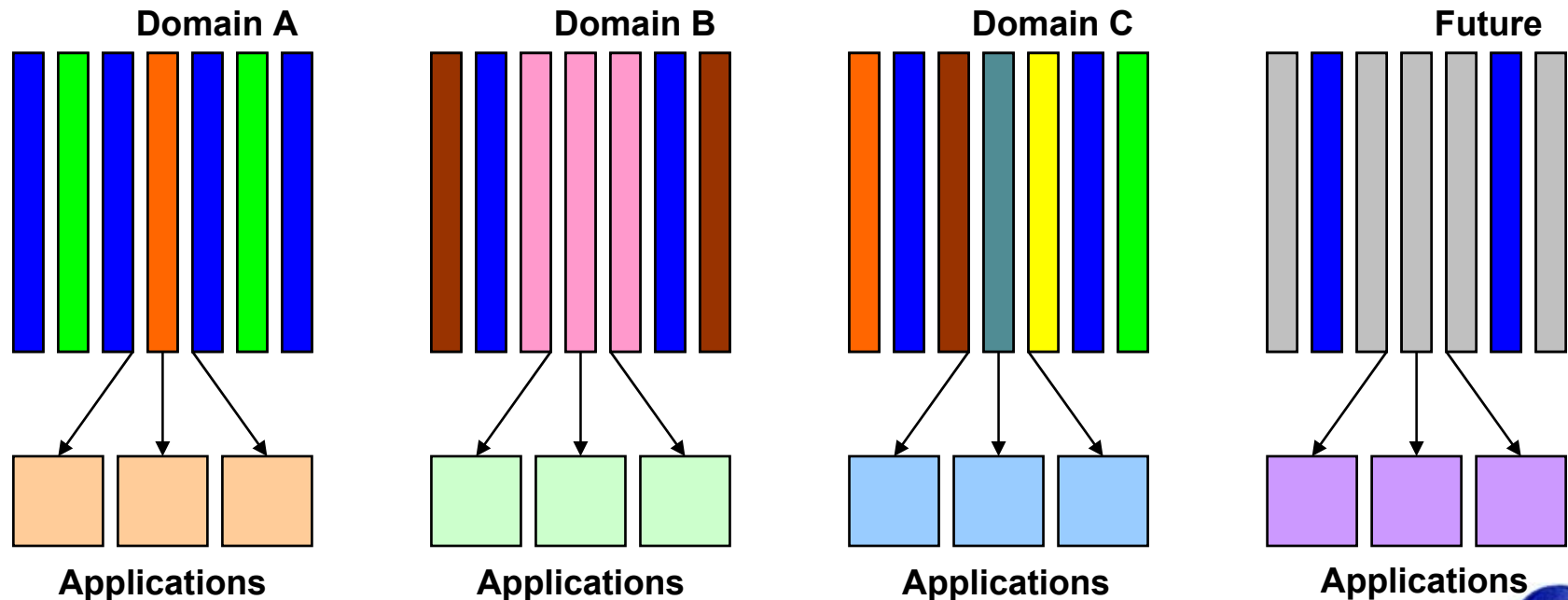
Application Specific Modular Block Architecture

Column
Based
ASMBL
Architecture



Feature Options

- | | |
|--|--|
|  Logic |  High-speed I/O |
|  DSP |  Hard IP |
|  Memory |  Mixed Signal |
|  Processing |  Future... |



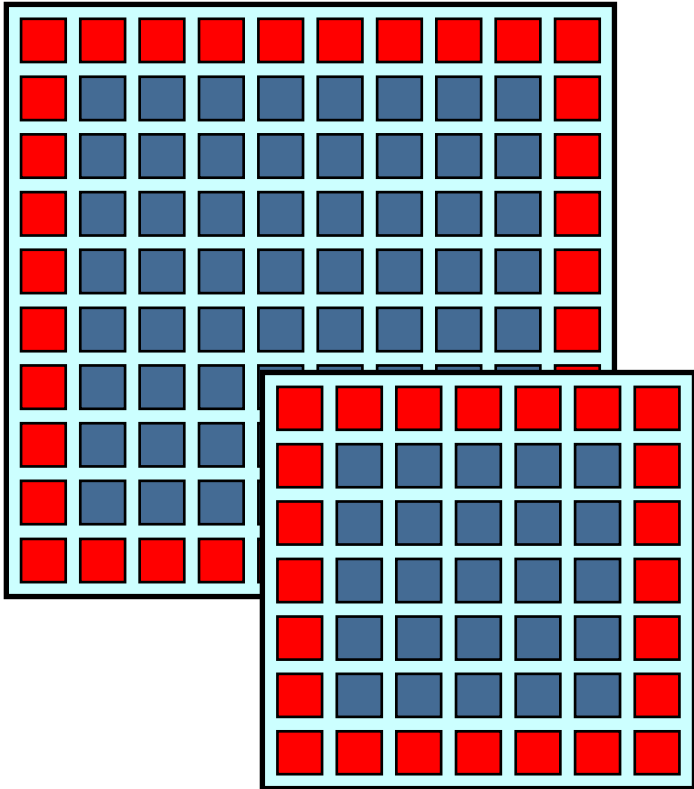
Addressing Geometric Constraints



ASMBL Addresses

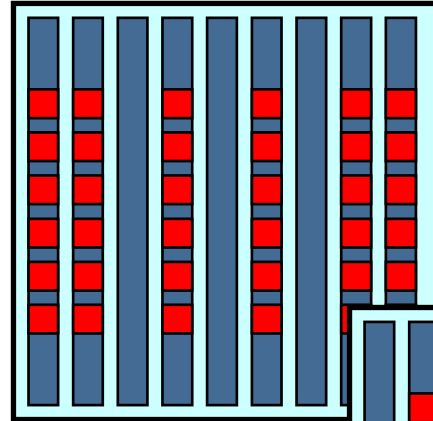
I/O and Array Dependency

Array increase, I/O increase



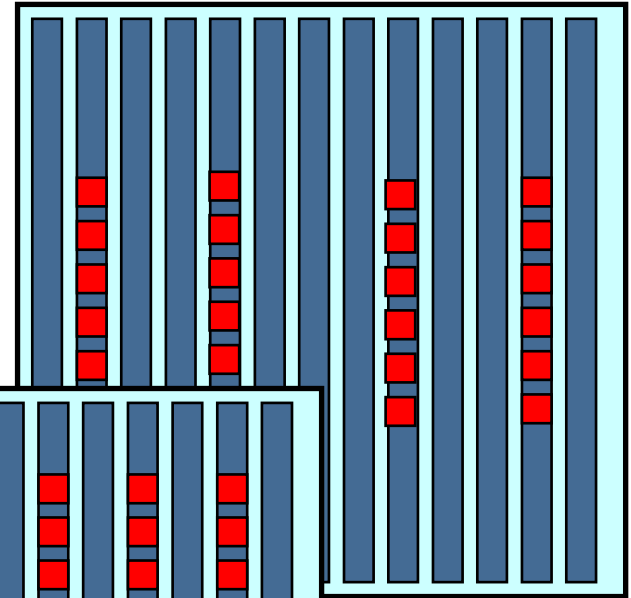
Peripheral I/O
dependent on array size

Array constant
I/O increase



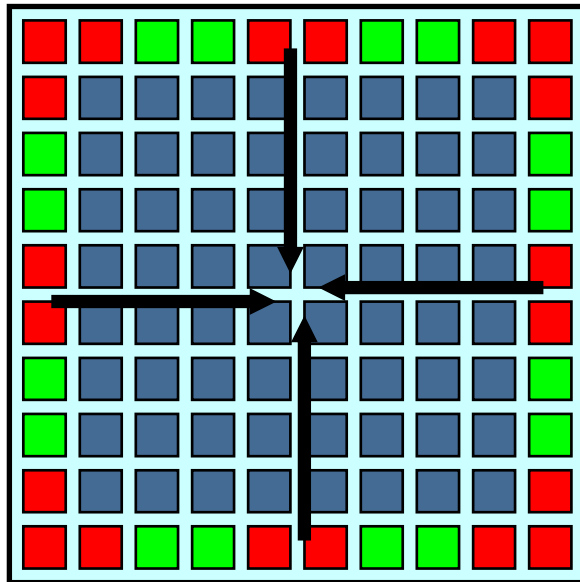
Column based I/O
independent of array size

Array increase, I/O constant

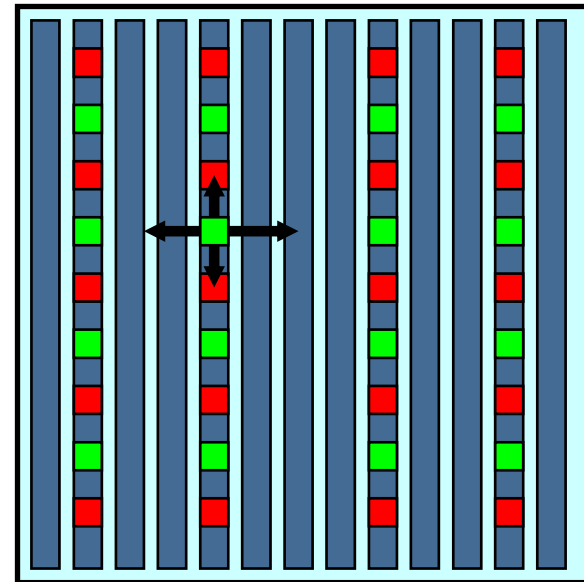


ASMBL Addresses PWR & GND Distribution

- New Pwr & Gnd distribution reduces voltage drop
- Switching reliability increase via higher thresholds



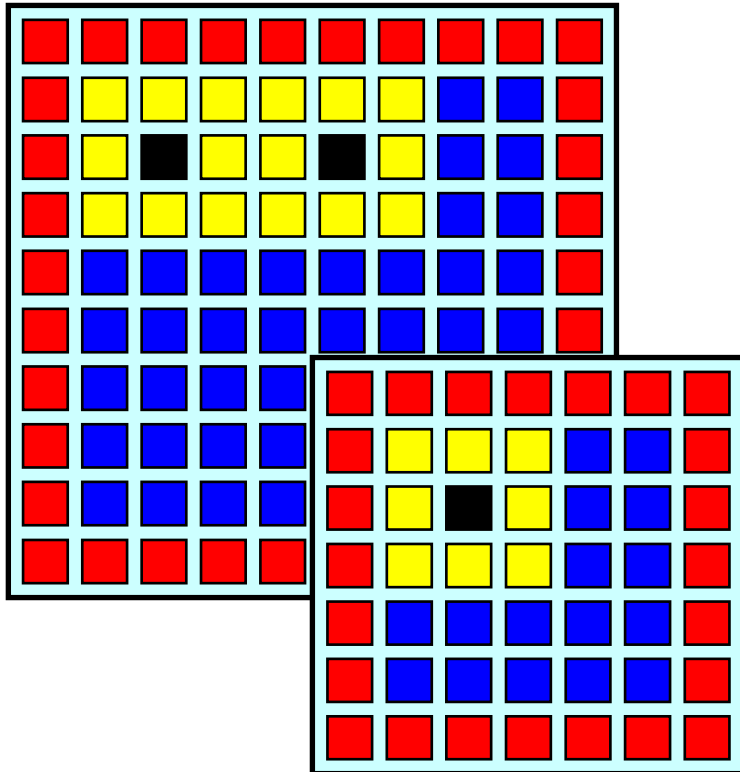
Traditional Architecture



ASMBL Architecture

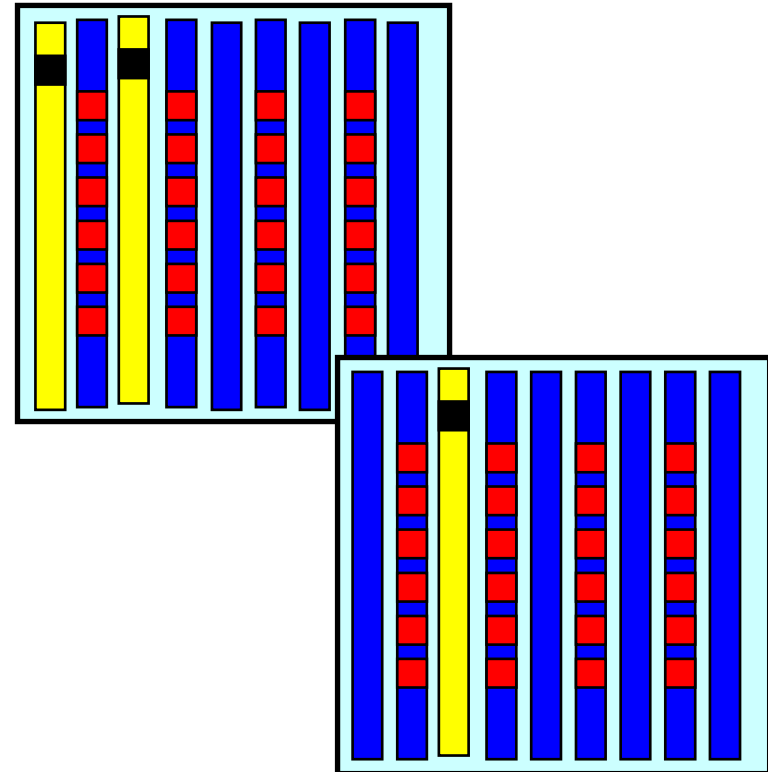
ASMBL Addresses Hard IP Scaling

Array size increase to
accommodate feature scaling



Traditional Architecture

Array size constant as
features scale independently

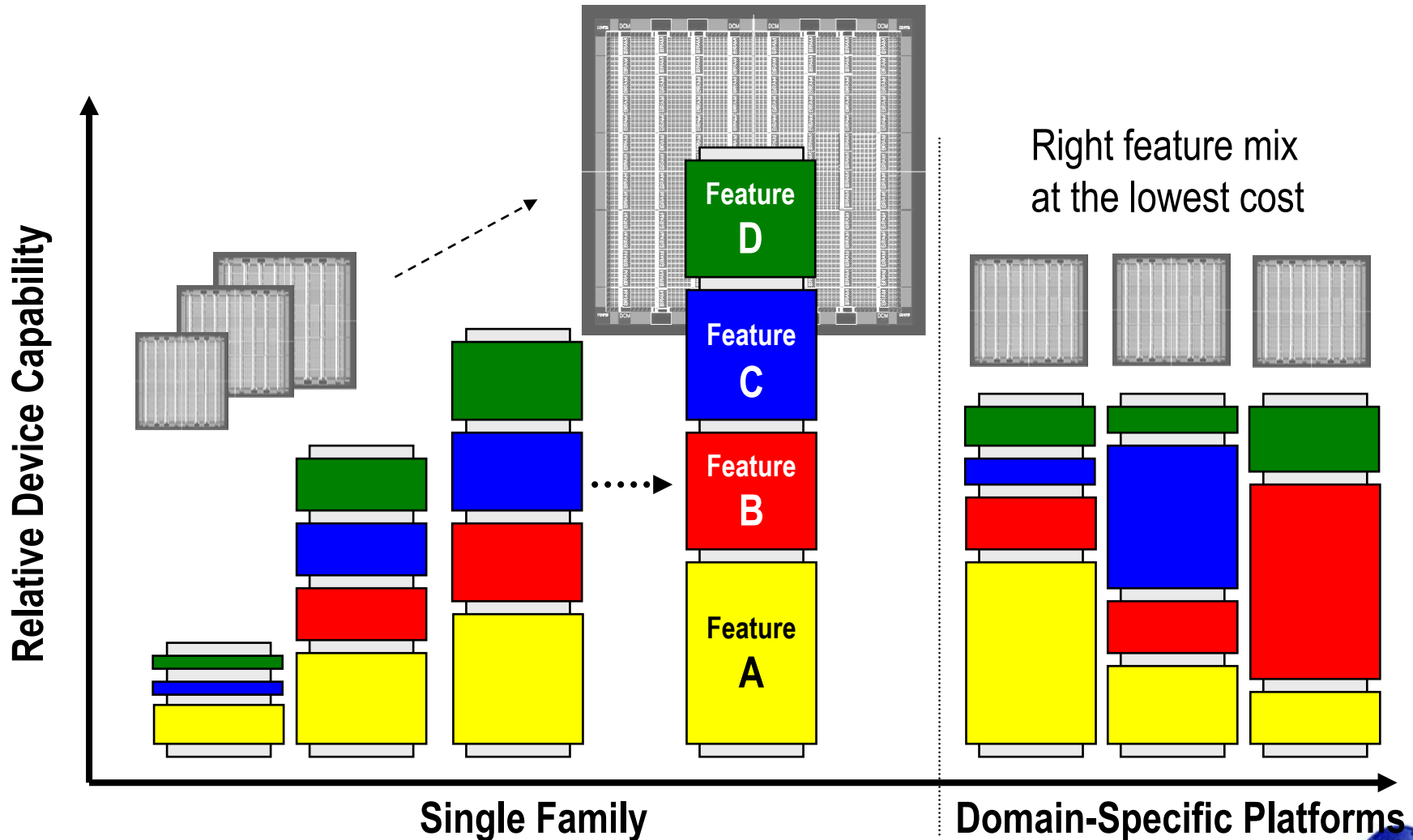


ASMBL Architecture

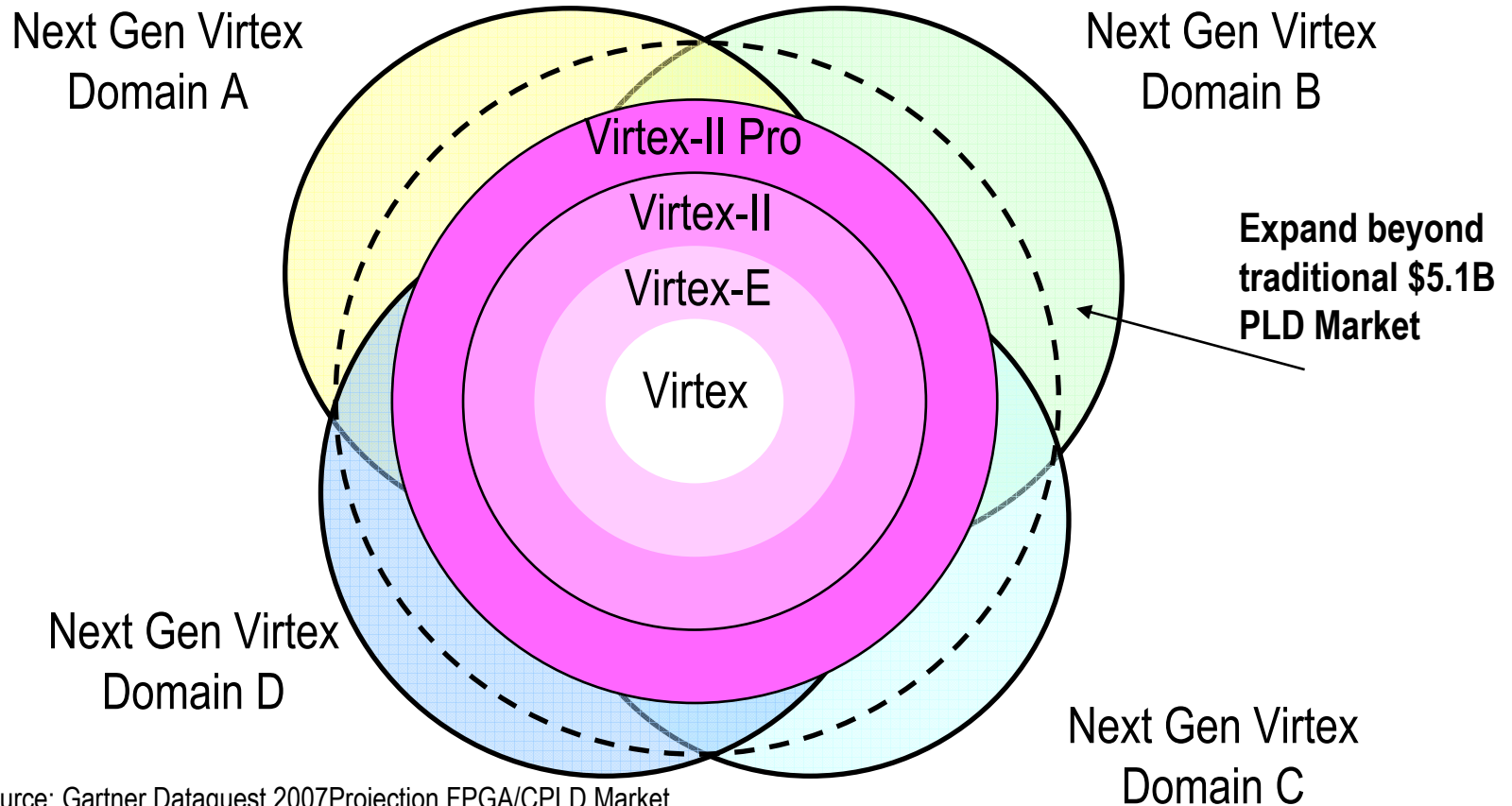
ASMBL Advantages

- Xilinx Benefits
 - Reduces time & risk for FPGA platform development
 - Enables cost-effective assembly of multiple platforms
 - Allows rapid response to new market demands
- Customer Benefits
 - Highest value solution at a given price point
 - Right feature mix for a given domain

ASMBL Enables Domain-Specific Platforms



Cost Effectively Expanding Xilinx FPGA Application Domains



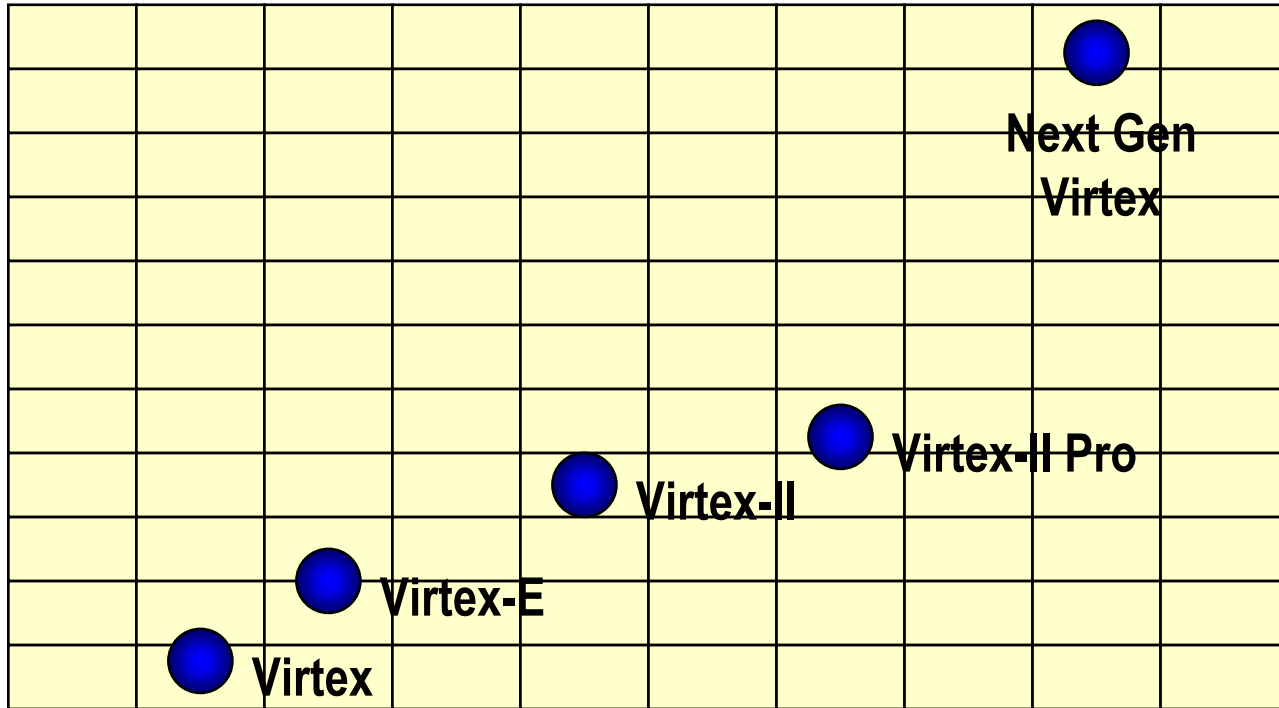
Market Data Source: Gartner Dataquest 2007 Projection FPGA/CPLD Market

Taking Advantage of Moore's Law

Millions of
Transistors

1000

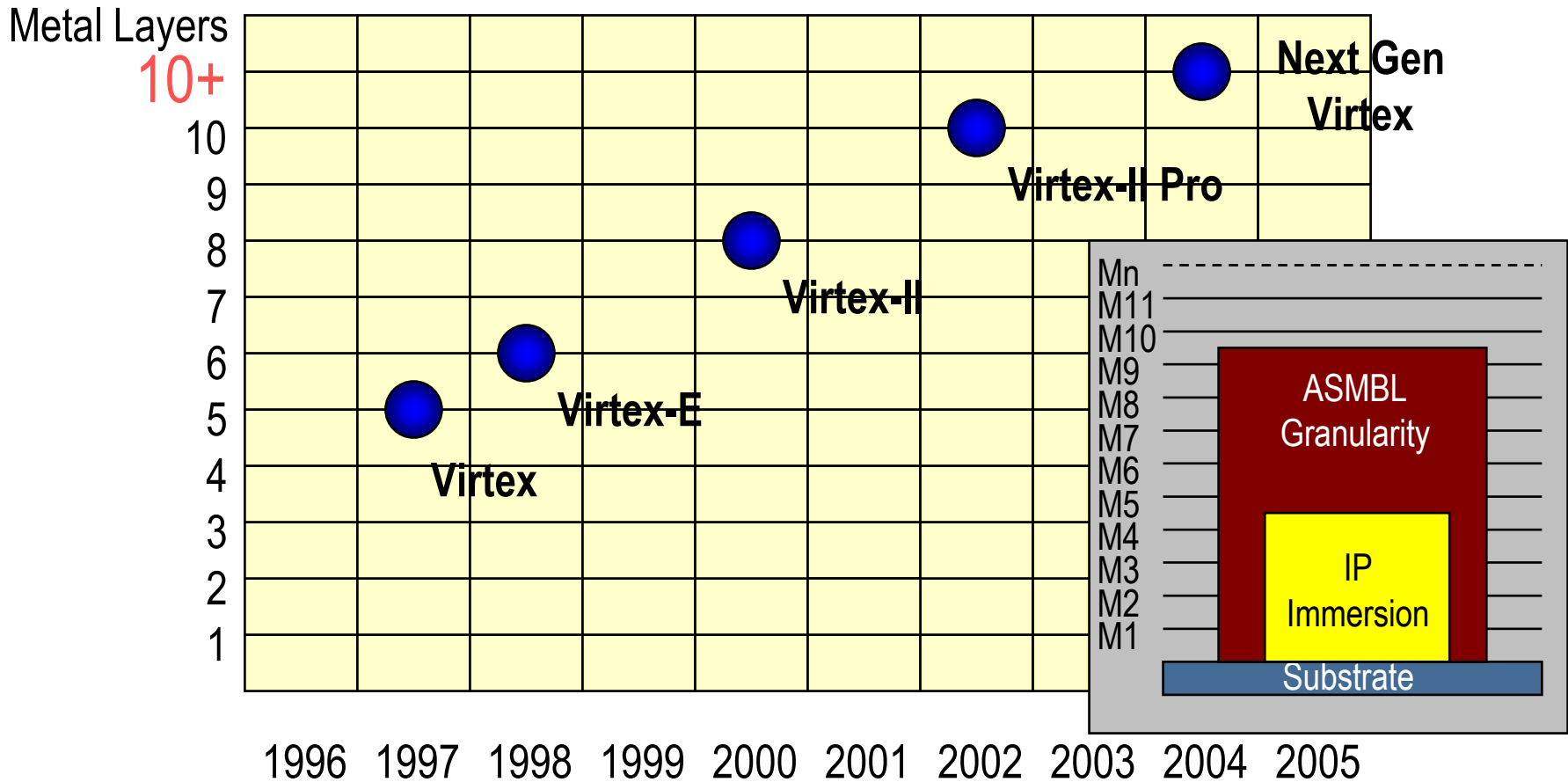
900
800
700
600
500
400
300
200
100



1996 1997 1998 1999 2000 2001 2002 2003 2004 2005

Transistor count increases, cost decreases

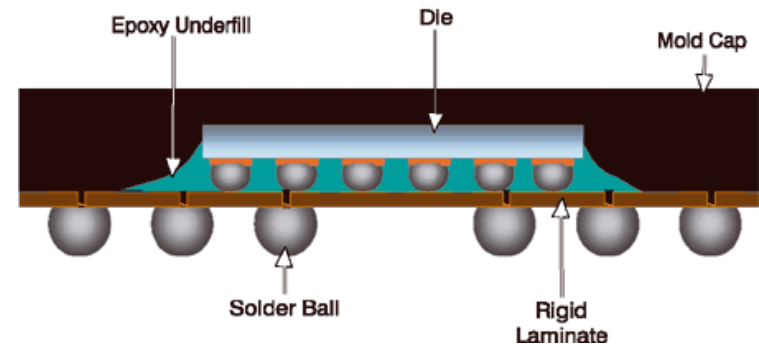
Taking Advantage of 10+ Layers of Metal



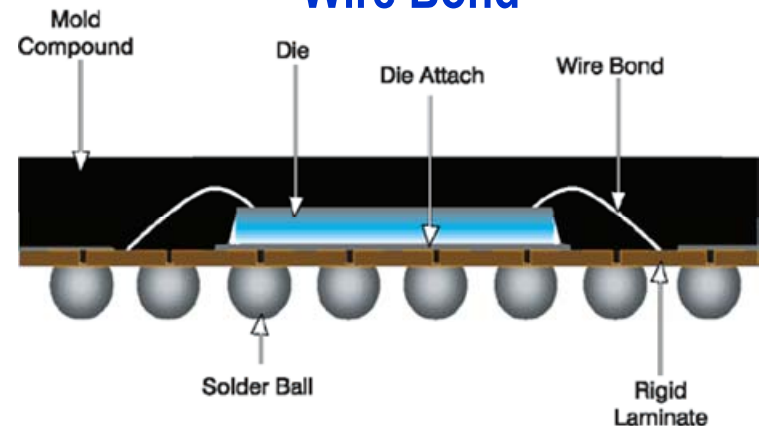
Taking Advantage of Advanced Packaging

- Flip Chip enables column based architecture
- Allows connecting to I/Os anywhere on the die
- Enhanced thermal dissipation

Flip Chip

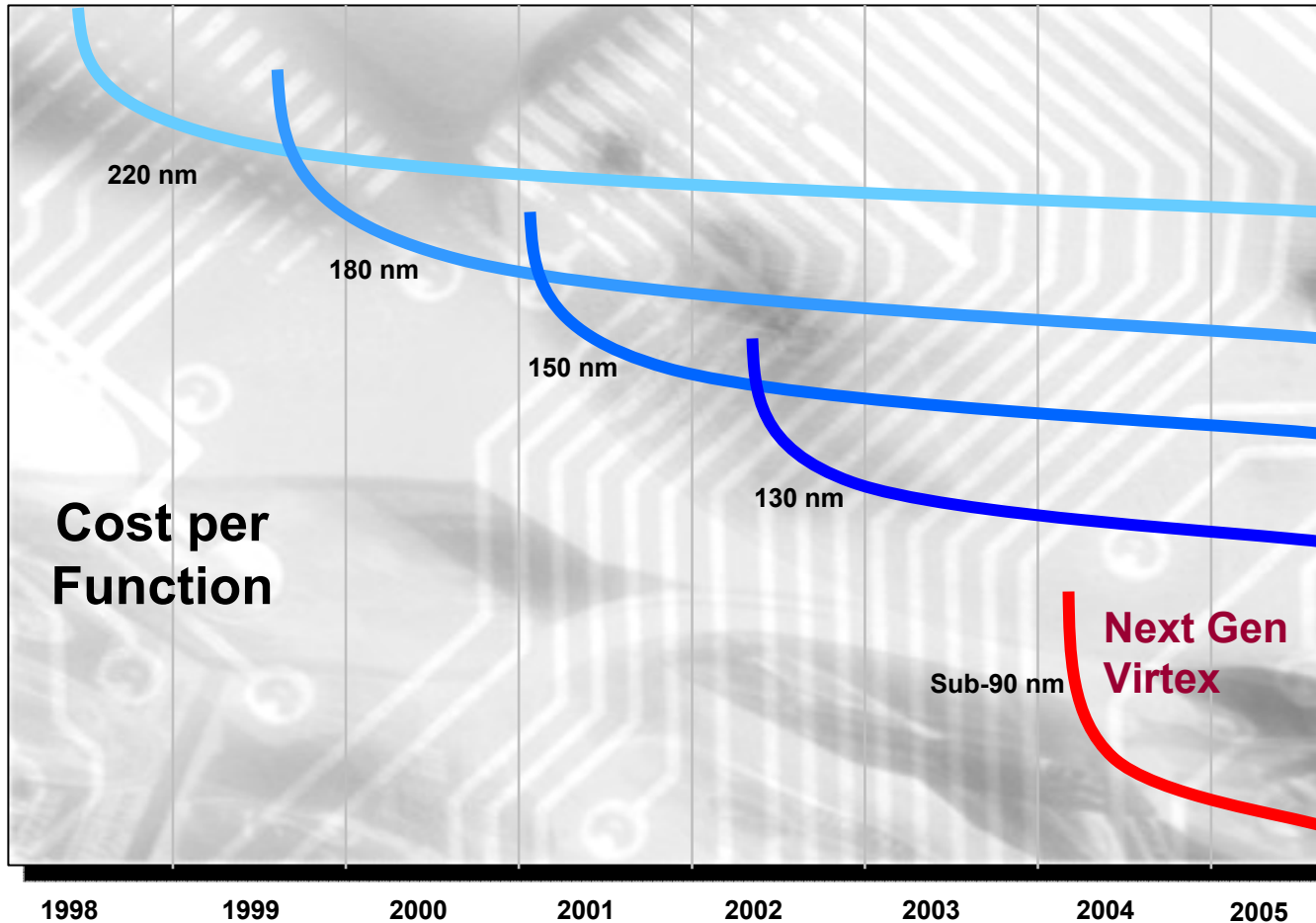


Wire Bond



Package source: Amkor Technology

Next Generation Cost Metrics



Old density based metrics
\$/LC and \$/Gate

New capability based metrics
\$/MAC/s or \$/BOPS
\$/Mbit of storage
\$/Gbps bandwidth
\$/Gbyte/s bandwidth
\$/DMIPS
\$/system functionality
\$/mixed signal

Conclusion

- ASMBL enables domain-specific Platform FPGAs
- Addresses traditional architectural limitations
- Highest value solution at a given price point

